

36th DAC (1999) Best Paper Award

This year, awards were made for the best papers in four categories. Winners were determined from detailed reviews of the accepted papers in the technical sessions. Each award is accompanied by a plaque and a cash award of \$400. The awards are given by ACM/SIGDA (Special Interest Group on Design Automation), IEEE/CAS (Institute of Electrical and Electronics Engineers/Circuits and Systems Society) and EDA Consortium (Electronic Design Automation Consortium).

Physical and Electrical Design Modeling, and Estimation

Paper 6.1: Area Optimization of VLSI Power/Ground Networks Via Sequence of Linear Programmings

Authors: Xiangdong Tan, C.J. Richard Shi, Dragos Lungeanu Jyh-Chwen Frank Lee, Li-Pen Yuan
Affiliation: *Univ. of Washington, Seattle, WA Avant! Corp., Fremont, CA*

Logic-Level Testing, Simulation and Synthesis

Paper 42.2: Improving the Test Quality for Scan-Based BIST Using a General Test Application Scheme

Authors: Huan-Chih Tsai, Kwang-Ting Cheng Sudipta Bhawmik
Affiliation: *Univ. of California, Santa Barbara, CA Lucent Technology, Princeton, NJ*

High-Level Synthesis, Verification, and Co-Design

Paper 18.1: Coverage Estimation for Symbolic Model Checking

Authors: Yatin V. Hoskote, Timothy Kam, Xudong Zhao Pei-Hsin Ho
Affiliation: *Intel Corp., Hillsboro, OR Synopsys, Inc., Beaverton, OR*

Design Methodology

• System Level Design Methodology

Paper 4.1: Common Case computation: A High Level Power Optimization Technique

Authors: Ganesh Lakshminarayana, Anand Raghunathan Kamal S. Khouri
Affiliation: *NEC USA, Princeton, NJ Princeton Univ., Princeton, NJ*
Author: Sujit Dey, Niraj K. Jha
Affiliation: *Univ. of California at San Diego, La Jolla, CA*

• Technology Driven Design Methodology

Paper 28.1: Reducing Cross Coupling Among Interconnect Wires in Deep Sub-micron Datapath Design

Author: Joon-Seo Yim Chong-Min Kyung
Affiliation: *LG CIT, Seoul, Korea KAIST, Taejeon, Korea*